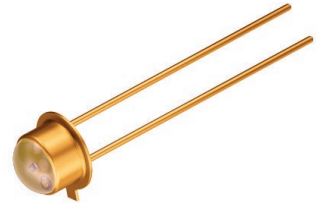


SFH 4841

Metal Can® TO18

Infrared Emitter (940 nm)



Applications

- Electronic Equipment
- Industrial Automation (Machine Controls, Light Barriers, Vision Controls)

Features:

- Package: clear epoxy
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- Wavelength 940nm
- Anode is electrically connected to the case
- Short switching times
- Spectral match with silicon photodetectors
- DIN humidity category in acc. with DIN 40 040 GQG

Ordering Information

| Type | Radiant intensity ¹⁾ $I_F = 100 \text{ mA}; t_p = 20 \text{ ms}$ I_e | Radiant intensity ¹⁾ typ. $I_F = 100 \text{ mA}; t_p = 20 \text{ ms}$ I_e | Ordering Code |
|-------------|---|---|---------------|
| SFH 4841 | 16 ... 80 mW/sr | 35 mW/sr | Q65111A6134 |
| SFH 4841-TU | 25 ... 80 mW/sr | 35 mW/sr | Q65112A4900 |

Discontinued

Maximum Ratings

$T_A = 25\text{ °C}$

| Parameter | Symbol | | Values |
|--|-----------|------|--------|
| Operating temperature | T_{op} | min. | -40 °C |
| | | max. | 100 °C |
| Storage temperature | T_{stg} | min. | -40 °C |
| | | max. | 100 °C |
| Forward current | I_F | max. | 100 mA |
| Surge current $t_p \leq 250\ \mu\text{s}; D = 0$ | I_{FSM} | max. | 1 A |
| Reverse voltage ²⁾ | V_R | max. | 12 V |
| Power consumption | P_{tot} | max. | 190 mW |
| ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2) | V_{ESD} | max. | 2 kV |

Characteristics

$I_F = 100 \text{ mA}$; $t_p = 20 \text{ ms}$; $T_A = 25 \text{ °C}$

| Parameter | Symbol | | Values |
|--|-----------------------------|--------------|----------------------|
| Peak wavelength | λ_{peak} | typ. | 950 nm |
| Centroid wavelength | $\lambda_{\text{centroid}}$ | typ. | 940 nm |
| Spectral bandwidth at 50% $I_{\text{rel,max}}$ (FWHM) | $\Delta\lambda$ | typ. | 42 nm |
| Half angle | φ | typ. | 32 ° |
| Dimensions of active chip area | L x W | typ. | 0.3 x 0.3 mm x mm |
| Distance chip surface to lens top | H | min. max. | 0.3 mm 0.7 mm |
| Rise time (10% / 90%) $I_F = 100 \text{ mA}$; $R_L = 50 \text{ }\Omega$ | t_r | typ. | 12 ns |
| Fall time (10% / 90%) $I_F = 100 \text{ mA}$; $R_L = 50 \text{ }\Omega$ | t_f | typ. | 12 ns |
| Forward voltage | V_F | typ. max. | 1.6 V 1.9 V |
| Forward voltage $I_F = 1 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | V_F | typ. max. | 3.6 V 4.6 V |
| Reverse current ²⁾ $V_R = 5 \text{ V}$ | I_R | max. | 10 μA |
| Radiant intensity ¹⁾ $I_F = 1 \text{ A}$; $t_p = 100 \text{ }\mu\text{s}$ | I_e | typ. | 160 mW/sr |
| Total radiant flux ³⁾ | Φ_e | typ. | 80 mW |
| Temperature coefficient of voltage | TC_V | typ. | -0.8 mV / K |
| Temperature coefficient of brightness | TC_I | typ. | -0.3 % / K |
| Temperature coefficient of wavelength | TC_λ | typ. | 0.3 nm / K |
| Thermal resistance junction case real | R_{thJC} | max. | 350 K / W |
| Thermal resistance junction ambient real | R_{thJA} | max. | 500 K / W |

Brightness Groups

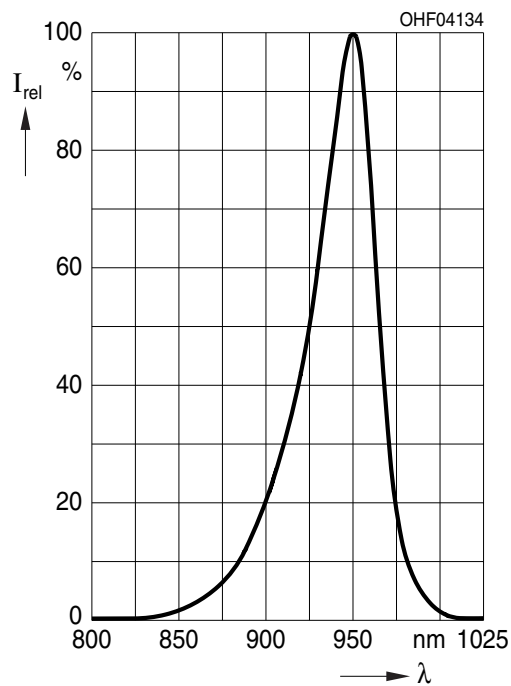
$T_A = 25\text{ °C}$

| Group | Radiant intensity | Radiant intensity |
|-------|--|--|
| | $I_F = 100\text{ mA}; t_p = 20\text{ ms}$ min. I_e | $I_F = 100\text{ mA}; t_p = 20\text{ ms}$ max. I_e |
| S | 16 mW/sr | 32 mW/sr |
| T | 25 mW/sr | 50 mW/sr |
| U | 40 mW/sr | 80 mW/sr |

Only one group in one packing unit (variation lower 2:1).

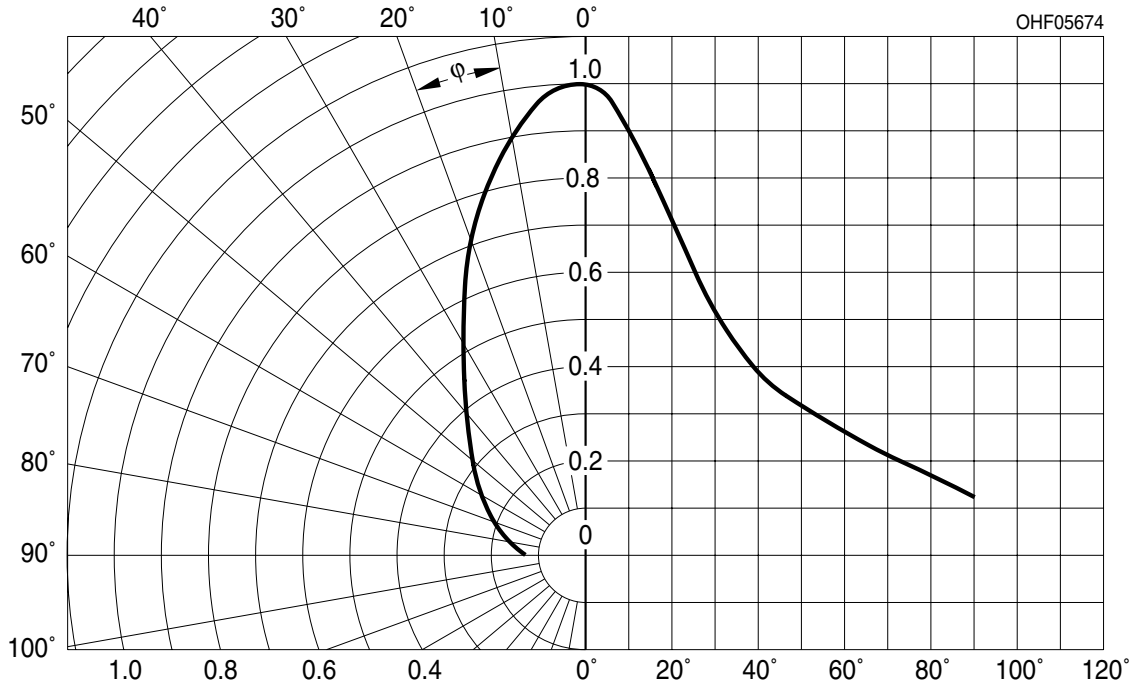
Relative Spectral Emission ^{4), 5)}

$I_{e,rel} = f(\lambda); I_F = 100\text{ mA}; t_p = 20\text{ ms}$



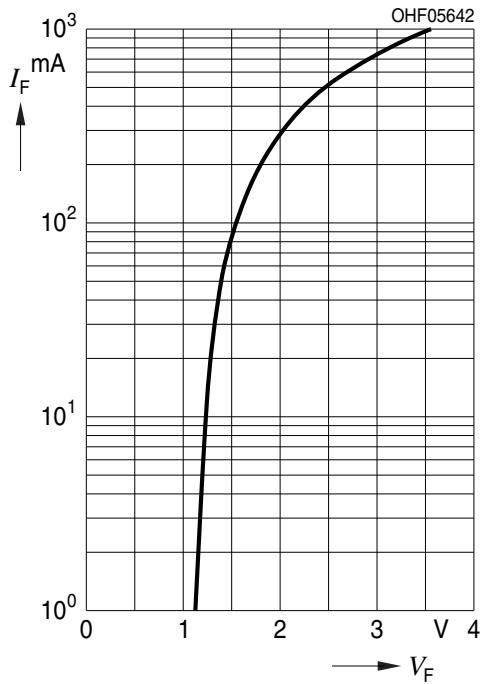
Radiation Characteristics 4), 5)

$I_{e,rel} = f(\varphi)$



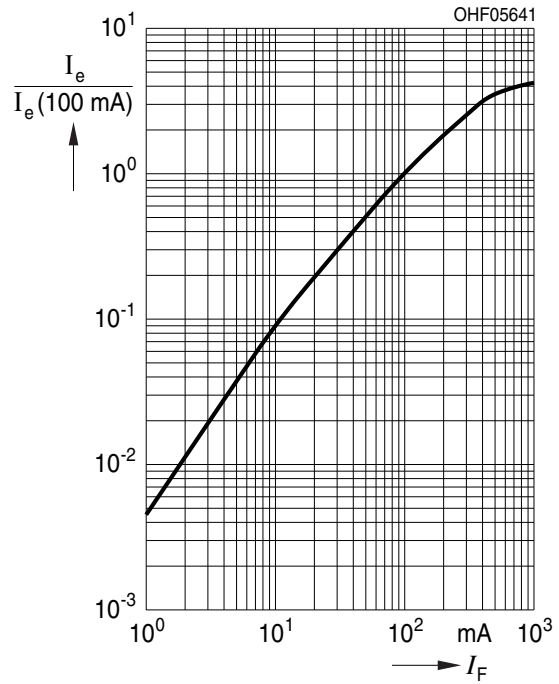
Forward current 4), 5)

$I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



Relative Radiant Intensity 4), 5)

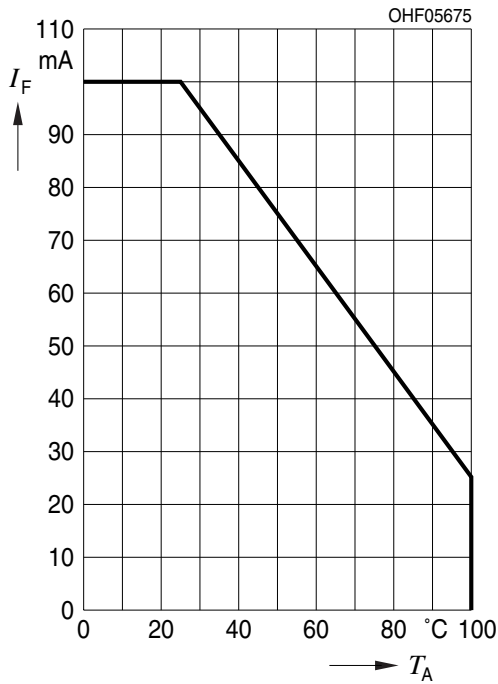
$I_e/I_e(100mA) = f(I_F)$; single pulse; $t_p = 100 \mu s$



Discontinued

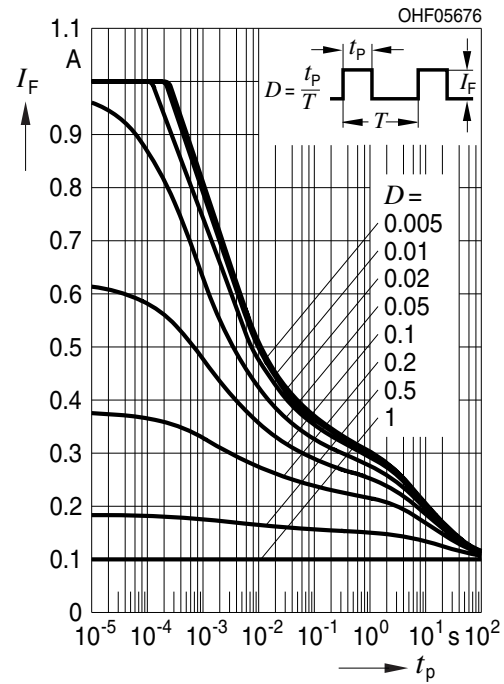
Max. Permissible Forward Current

$I_{F,max} = f(T_A)$; $R_{th,ja} = 500K / W$; single pulse



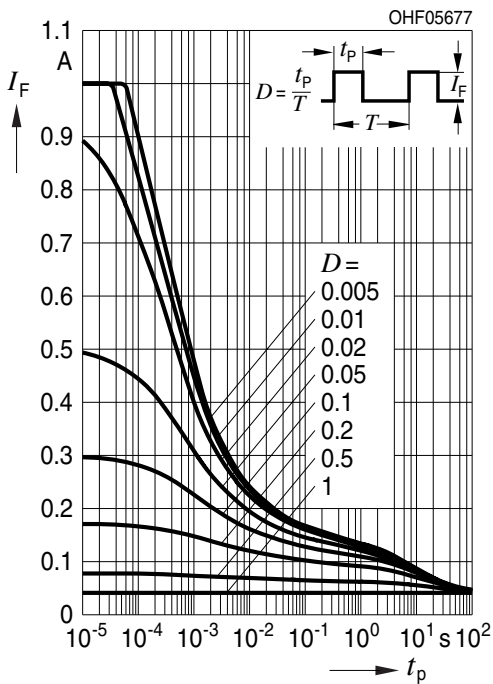
Permissible Pulse Handling Capability

$I_F = f(t_p)$; duty cycle $D = \text{parameter}$; $T_A = 25^\circ C$



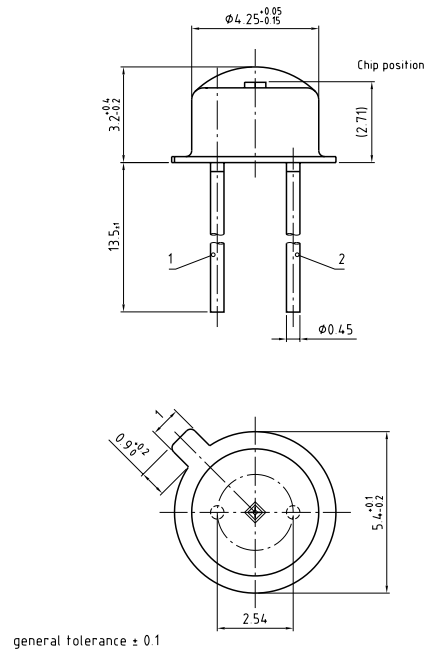
Permissible Pulse Handling Capability

$I_F = f(t_p)$; duty cycle $D = \text{parameter}$; $T_A = 85^\circ C$



Discontinued

Dimensional Drawing ⁶⁾



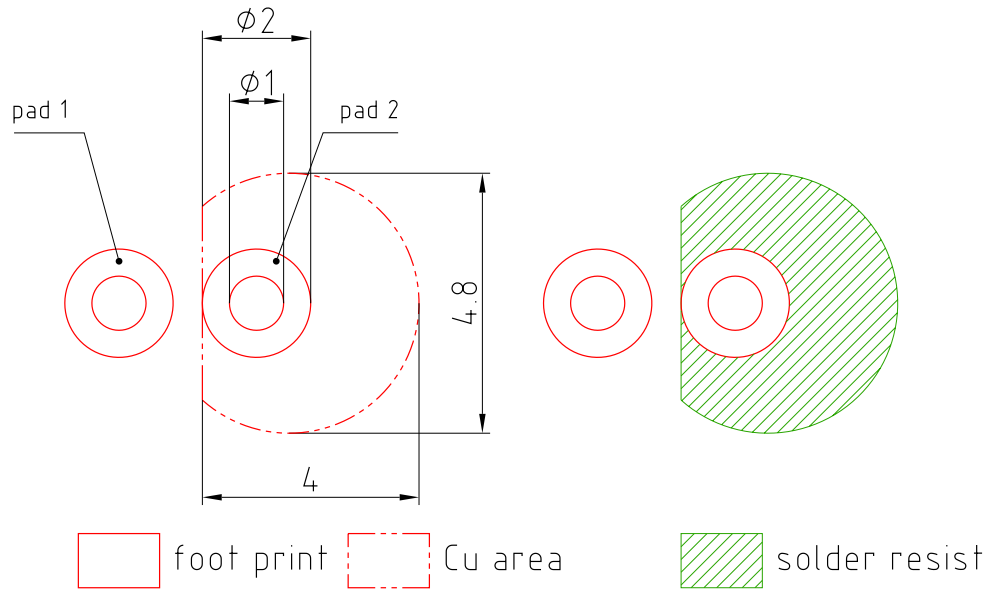
C63062-A4263-A1-03

Further Information

Approximate Weight: 180.0 mg

| Pin | Description |
|-----|-------------|
| 1 | Anode |
| 2 | Cathode |

Recommended Solder Pad ⁶⁾

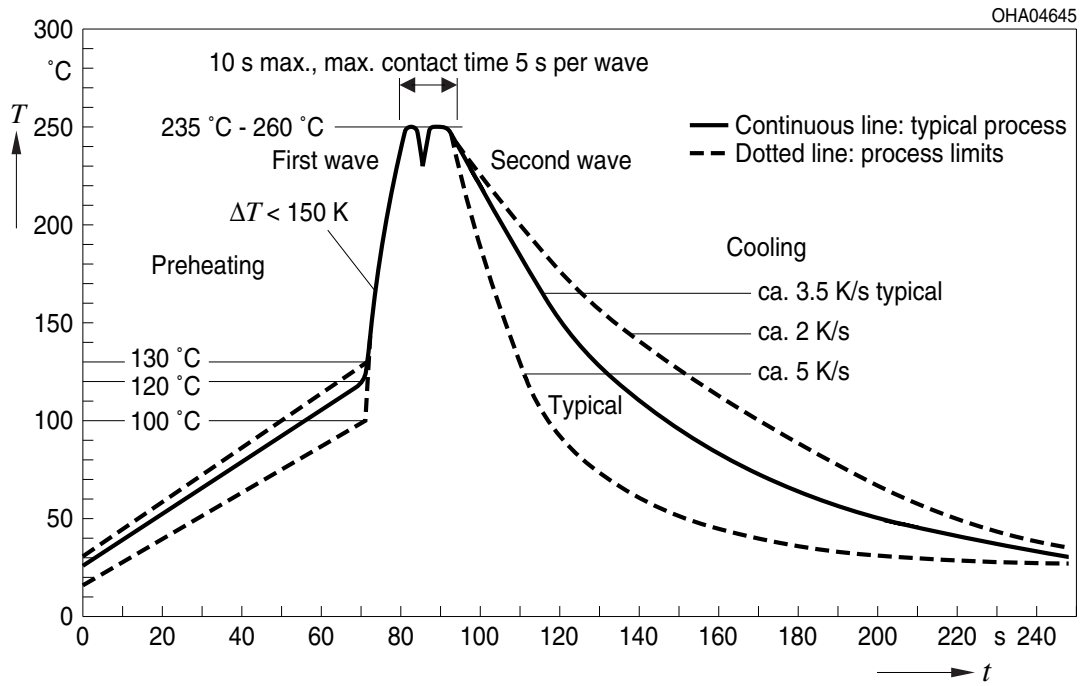


E062.3010.188-01

Pad 1: cathode

TTW Soldering

IEC-61760-1 TTW



Discontinued

Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

- 1) **Radiant intensity:** Measured at a solid angle of $\Omega = 0.01$ sr
- 2) **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- 3) **Total radiant flux:** Measured with integrating sphere.
- 4) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 5) **Testing temperature:** TA = 25°C (unless otherwise specified)
- 6) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.

Revision History

| Version | Date | Change |
|---------|------------|--------------|
| 1.4 | 2019-07-15 | Discontinued |

Published by OSRAM Opto Semiconductors GmbH EU RoHS and China RoHS compliant product
Leibnizstraße 4, D-93055 Regensburg
www.osram-os.com © All Rights Reserved.



此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9